

innodisk

DATA
INTELLIGENCE



ELEVATING INDUSTRIAL PERFORMANCE WITH DRAM MODULE ADD-ON SELECTION

DRAM modules may face unique challenges in industrial applications, such as vibration and temperature fluctuations. Innodisk's tailored solutions feature upgrades like heat spreaders, rugged clips, conformal coating, and Side Fill technology. These enhancements ensure optimal performance, durability, and reliability in demanding industrial environments, making our solutions indispensable for industrial use.



Heat Spreader



Rugged Clips



Conformal Coating



Side Fill



INNODISK'S DRAM SOLUTIONS: ENGINEERED FOR INDUSTRIAL DEMANDS

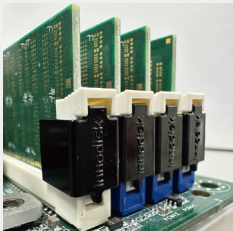
Uncover how our innovative DRAM module add-on selection addresses the demanding challenges of industrial environments, fortifying module strength, enhancing reliability, and ensuring peak performance for extended longevity.

Heat Spreader



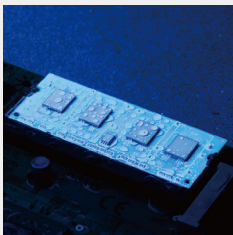
Our specially designed DDR5 long DIMM heat spreader, leveraging fin design and high-performance thermal interface materials (TIM), effectively manages system heat, ensuring peak performance and reliability in industrial environments. Our innovative, robust structural design also actively strengthens connections to withstand vibrations encountered in industrial settings, ensuring uninterrupted operation even under challenging conditions.

Rugged Clips



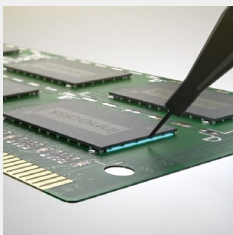
In response to the intense vibrations, our patent rugged clips are made from robust PANLITE® material. They provide a reliable and cost-effective solution to secure DRAM modules from dislodging from DIMM slots without risking warranties or functionality.

Conformal Coating



Innodisk's conformal coating protects DRAM modules from dust, pollution, humidity, and corrosion, ensuring uniformity, integrity, and reliability even in the most challenging industrial settings. This protective layer acts as a barrier, defending against potential scratches or disturbances that could affect the operation of vital components.

Side Fill



Innodisk's Side Fill technology revolutionizes the robustness of DRAM modules by fortifying IC connections with a strategic application of acrylic resin along three sides of the IC. This ensures stability without causing heat buildup and simplifies maintenance procedures. Our approach prioritizes reliability to provide robust support for ICs in demanding industrial environments.